

In the Application of:

JAKOB et al.

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IN THE SPECIFICATION:

Please replace the paragraph on page 23 at lines 23-27 with the following:

Fig. 3: a wafer after step 3, after the application of a ~~protective and~~ carrier layer 4 by application of a plastics composition consisting for example of a polymer (e.g. polyamide). In this connection it may be advantageous to distribute and/or smooth the applied composition by means of suitable methods such as for example spincoating. Carrier layer 4 preferably provides protection for interlayer 3.

Please replace the paragraph on page 25 at lines 21-25 with the following:

Fig. 14: an alternative to step 13: it may be advantageous and/or necessary to place and/or bond the wafer via its rear side on/to ~~another a second~~ film and/or ~~another~~ carrier (for example carrier films such as Blue Tape) 18, if necessary to fix the wafer by means of holding frames 20, as well as to rotate the wafer.

Please replace the paragraph on page 42 at lines 5-9 with the following:

Fig. 17 is a detailed view of the region 100 identified with a magnifying glass in Fig. 16: a small part of the silicon layer 1 without electronic components, the active layer 2 with electronic components, the interlayer 3 and a part of the carrier layer 4 are shown. Within the interlayer 3 the dehesive zone 3a and the adhesive zone 3b are highlighted.